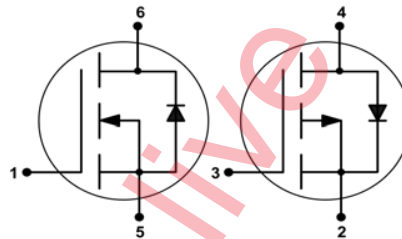
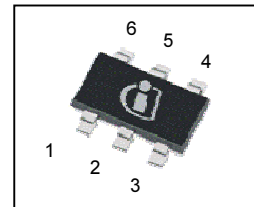


OptiMOS™2 + OptiMOS™-P 2 Small Signal Transistor
Features

- Complementary P + N channel
- Enhancement mode
- Super Logic level (2.5V rated)
- Avalanche rated
- Qualified according to AEC Q101
- 100% lead-free; RoHS compliant

Product Summary

		P	N	
V_{DS}		-20	20	V
$R_{DS(on),max}$	$V_{GS}=\pm 4.5\text{ V}$	150	140	mΩ
	$V_{GS}=\pm 2.5\text{ V}$	280	250	
I_D		-1.5	1.5	A


PG-TSOP6


Type	Package	Tape and Reel Information	Marking	Lead Free	Packing
BSL215C	PG-TSOP-6	L6327: 3000 pcs / reel	sPH	Yes	Non dry

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified ¹⁾

Parameter	Symbol	Conditions	Value		Unit
			P	N	
Continuous drain current	I_D	$T_A=25\text{ °C}$	-1.5	1.5	A
		$T_A=70\text{ °C}$	-1.2	1.2	
Pulsed drain current	$I_{D,pulse}$	$T_A=25\text{ °C}$	-6	6	
Avalanche energy, single pulse	E_{AS}	P: $I_D=-1.5\text{ A}$, N: $I_D=1.5\text{ A}$, $R_{GS}=25\text{ Ω}$	11	3.7	mJ
Gate source voltage	V_{GS}		±12		V
Power dissipation	P_{tot}	$T_A=25\text{ °C}$	0.5		W
Operating and storage temperature	T_j, T_{stg}		-55 ... 150		°C
ESD class		JESD22-A114-HBM	0 (<250V)		
Soldering temperature	T_{solder}		260		°C
IEC climatic category; DIN IEC 68-1			55/150/56		

¹⁾ Remark: only one of both transistors active

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Thermal characteristics

Thermal resistance, junction - ambient	P	R_{thJA}	minimal footprint ²⁾	-	-	250	K/W
	N						

Electrical characteristics, at $T_j=25\text{ °C}$, unless otherwise specified
Static characteristics

Drain-source breakdown voltage	P	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=-250\text{ }\mu\text{A}$	-	-	-20	V
	N		$V_{GS}=0\text{ V}, I_D=250\text{ }\mu\text{A}$	20	-	-	
Gate threshold voltage	P	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-11\text{ }\mu\text{A}$	-1.2	-0.9	-0.6	
	N		$V_{DS}=V_{GS}, I_D=3.7\text{ }\mu\text{A}$	0.7	0.95	1.2	
Zero gate voltage drain current	P	I_{DSS}	$V_{DS}=-20\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ °C}$	-	-	-1	μA
	N		$V_{DS}=20\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ °C}$	-	-	1	
	P		$V_{DS}=-20\text{ V}, V_{GS}=0\text{ V}, T_j=150\text{ °C}$	-	-	-100	
	N		$V_{DS}=20\text{ V}, V_{GS}=0\text{ V}, T_j=150\text{ °C}$	-	-	100	
Gate-source leakage current	P	I_{GSS}	$V_{GS}=\pm 12\text{ V}, V_{DS}=0\text{ V}$	-	-	± 100	nA
	N						
Drain-source on-state resistance	P	$R_{DS(on)}$	$V_{GS}=-2.5\text{ V}, I_D=-1.1\text{ A}$	-	163	280	m Ω
	N		$V_{GS}=2.5\text{ V}, I_D=0.7\text{ A}$	-	173	250	
	P		$V_{GS}=-4.5\text{ V}, I_D=-1.5\text{ A}$	-	102	150	
	N		$V_{GS}=4.5\text{ V}, I_D=1.5\text{ A}$	-	108	140	
Transconductance	P	g_{fs}	$ V_{DS} >2 I_D R_{DS(on)max}, I_D=-1.2\text{ A}$	-	4.5	-	S
	N		$ V_{DS} >2 I_D R_{DS(on)max}, I_D=1.2\text{ A}$	-	4	-	

²⁾ Performed on 40mm² FR4 PCB. The traces are 1mm wide, 70 μm thick and 20mm long; they are present on both sides of the PCB

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics

Input capacitance	P	C_{iss}	$V_{GS}=0\text{ V}$, P: $V_{DS}=-10\text{ V}$, N: $V_{DS}=10\text{ V}$, $f=1\text{ MHz}$	-	270	346	pF	
	N			-	110	143		
Output capacitance	P	C_{oss}		-	110	128		
	N			-	46	62		
Reverse transfer capacitance	P	C_{rss}		-	94	128		
	N			-	6.1	9		
Turn-on delay time	P	$t_{d(on)}$		-	6.7		ns	
	N			-	4.1	-		
Rise time	P	t_r		P: $V_{DD}=-10\text{ V}$, $V_{GS}=-4.5\text{ V}$, $R_G=6\ \Omega$, $I_D=-1.5\text{ A}$	-	9.7	-	
	N				-	7.6	-	
Turn-off delay time	P	$t_{d(off)}$	N: $V_{DD}=10\text{ V}$, $V_{GS}=4.5\text{ V}$, $R_G=6\ \Omega$, $I_D=1.5\text{ A}$		-	14.5	-	
	N				-	6.8	-	
Fall time	P	t_f			-	14.0	-	
	N				-	1.4	-	

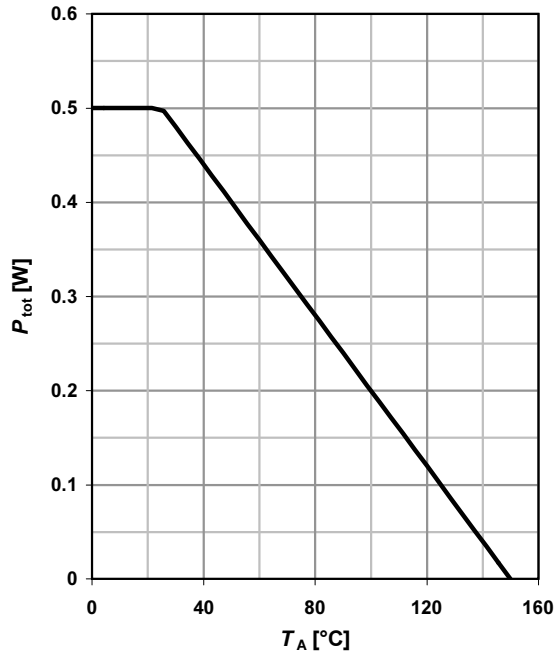
Gate Charge Characteristics

Gate to source charge	P	Q_{gs}	$V_{DD}=-10\text{ V}$, $I_D=-1.5\text{ A}$, $V_{GS}=0\text{ to }-5\text{ V}$	-	-0.49	-	nC	
Gate to drain charge		Q_{gd}		-	-1.9	-		
Switching charge		Q_g		-	-3.0	-		
Gate plateau voltage		$V_{plateau}$		-	-1.9	-		
Gate to source charge	N	Q_{gs}		$V_{DD}=10\text{ V}$, $I_D=1.5\text{ A}$, $V_{GS}=0\text{ to }4.5\text{ V}$	-	0.24	-	
Gate to drain charge		Q_{gd}			-	0.2	-	
Switching charge		Q_g			-	0.73	-	
Gate plateau voltage		$V_{plateau}$			-	2.2	-	

Parameter	Symbol	Conditions	Values			Unit	
			min.	typ.	max.		
Reverse Diode							
Diode continuous forward current	P	I_S	$T_C=25\text{ °C}$	-	-	-0.5	A
	N			-	-	0.5	
Diode pulse current	P	$I_{S,pulse}$		-	-	-6	
	N			-	-	6	
Diode forward voltage	P	V_{SD}	$V_{GS}=0\text{ V}, I_F=-1.5\text{ A}, T_j=25\text{ °C}$	-	-0.8	-1.1	V
	N		$V_{GS}=0\text{ V}, I_F=1.5\text{ A}, T_j=25\text{ °C}$	-	0.8	1.1	
Reverse recovery time	P	t_{rr}	$V_R=\pm 10\text{ V}, I_F=I_S, di_F/dt=100\text{ A}/\mu\text{s}$	-	21	-	ns
	N			-	8.4	-	
Reverse recovery charge	P	Q_{rr}		-	-3.7	-	nC
	N			-	1.7	-	

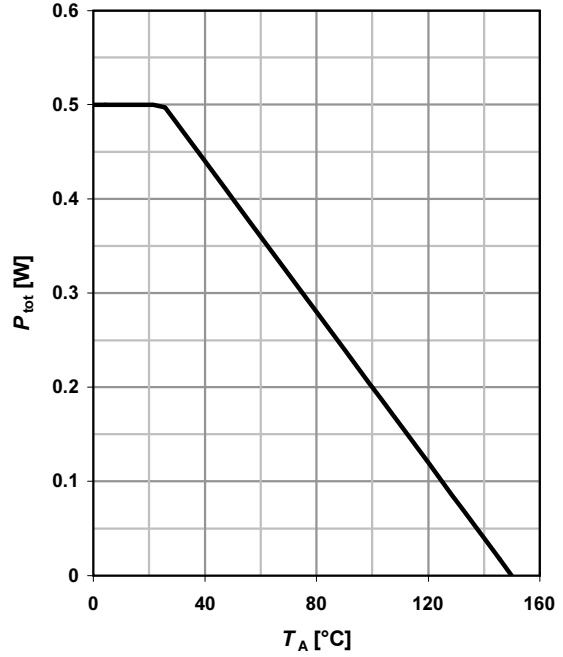
1 Power dissipation (P)

$$P_{tot}=f(T_A)$$



2 Power dissipation (N)

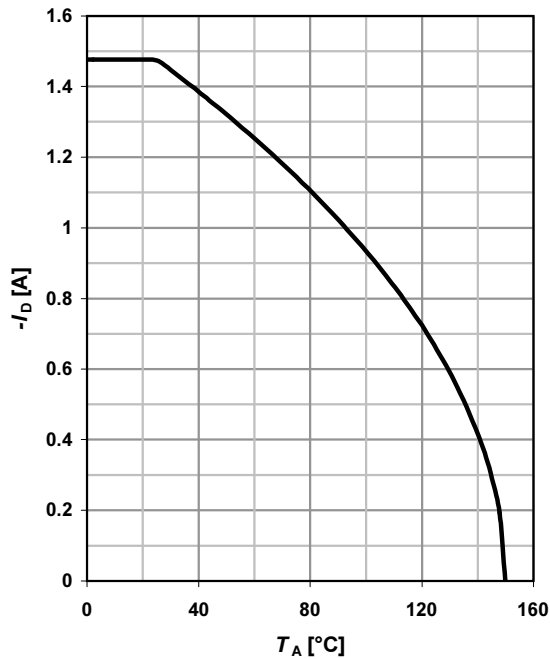
$$P_{tot}=f(T_A)$$



3 Drain current (P)

$$I_D=f(T_A)$$

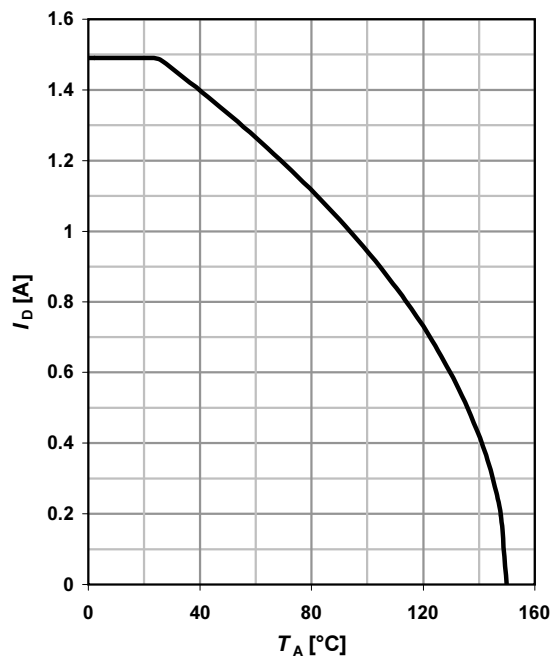
parameter: $V_{GS} \leq 4.5$ V



4 Drain current (N)

$$I_D=f(T_A)$$

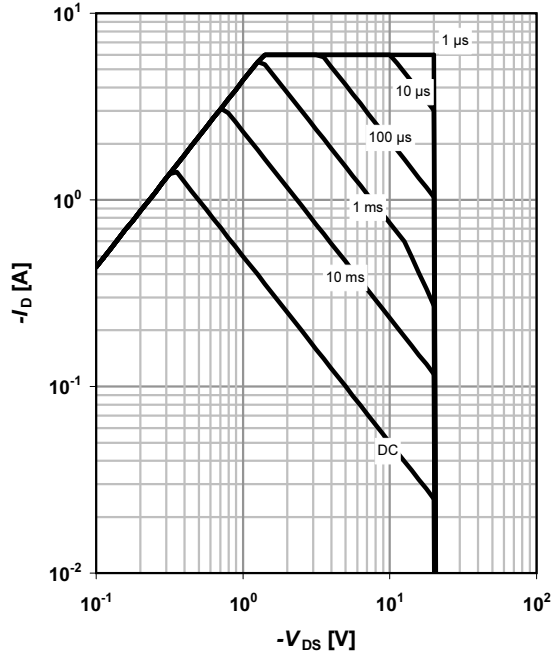
parameter: $V_{GS} \geq 4.5$ V



5 Safe operating area (P)

$I_D=f(V_{DS}); T_A=25\text{ }^\circ\text{C}; D=0$

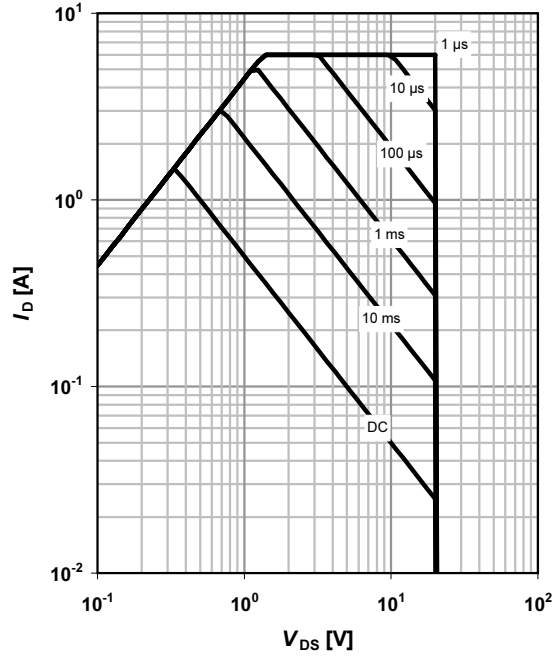
parameter: t_p



6 Safe operating area (N)

$I_D=f(V_{DS}); T_A=25\text{ }^\circ\text{C}; D=0$

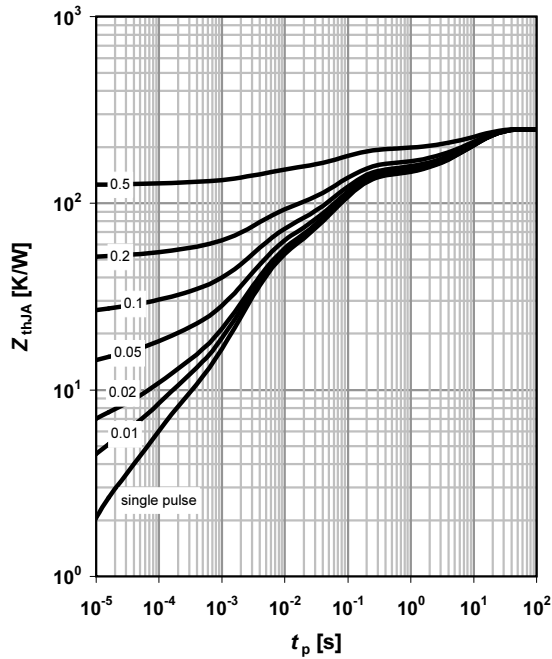
parameter: t_p



7 Max. transient thermal impedance (P)

$Z_{thJA}=f(t_p)$

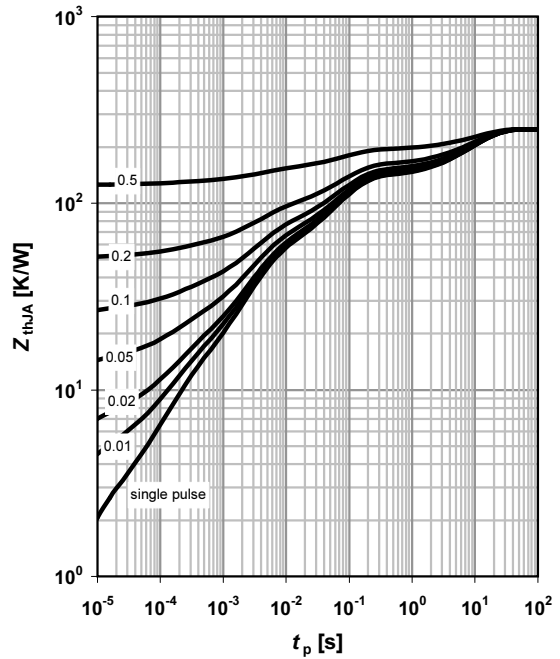
parameter: $D=t_p/T$



8 Max. transient thermal impedance (N)

$Z_{thJA}=f(t_p)$

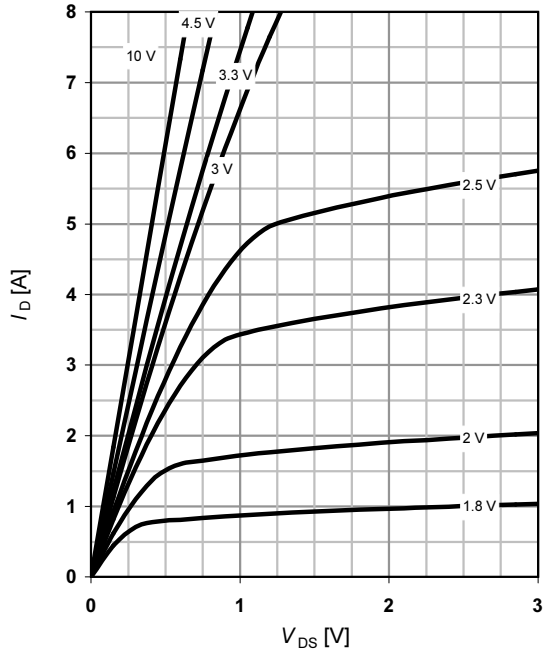
parameter: $D=t_p/T$



9 Typ. output characteristics (P)

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}$

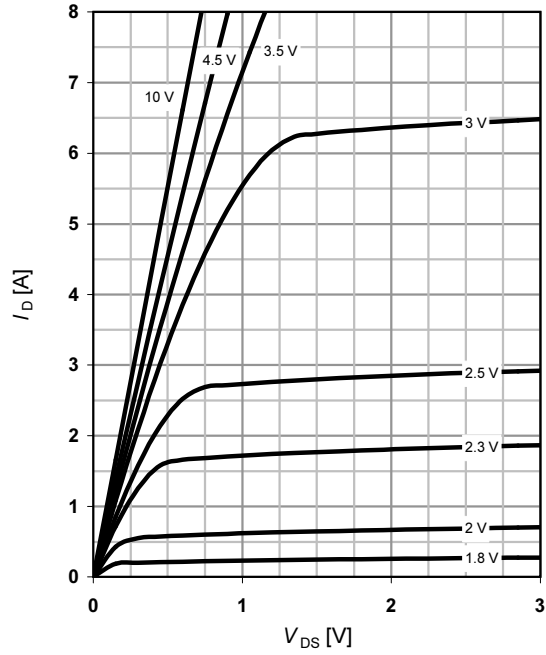
parameter: V_{GS}



10 Typ. output characteristics (N)

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}$

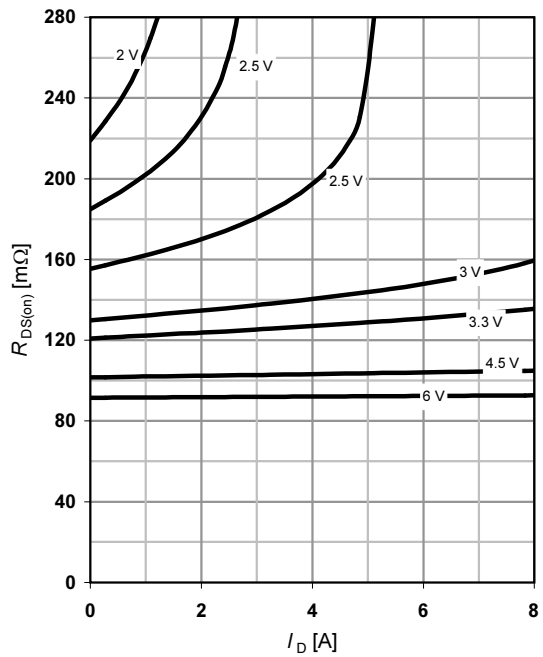
parameter: V_{GS}



11 Typ. drain-source on resistance (P)

$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}$

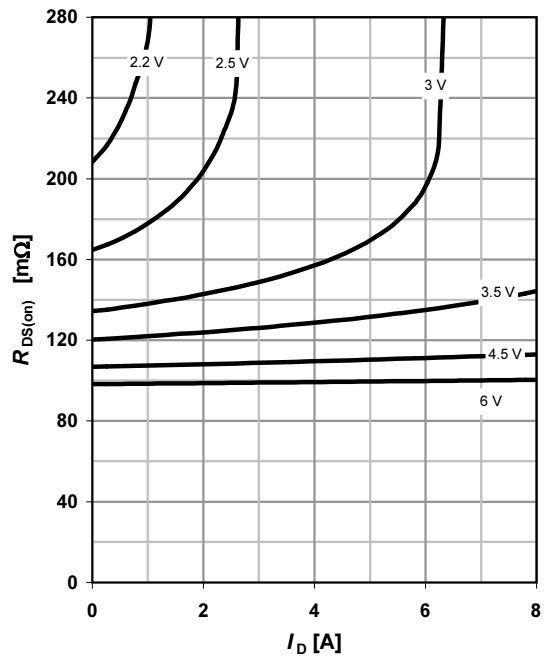
parameter: V_{GS}



12 Typ. drain-source on resistance (N)

$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}$

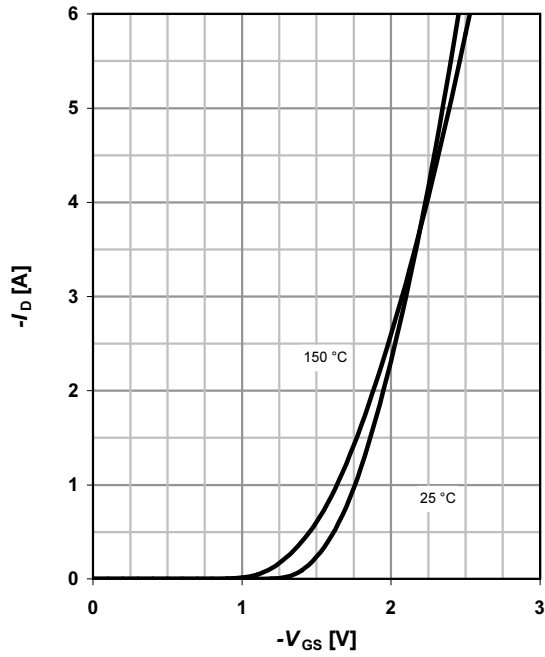
parameter: V_{GS}



13 Typ. transfer characteristics (P)

$$I_D = f(V_{GS}); |V_{DS}| > 2 |I_D| R_{DS(on)max}$$

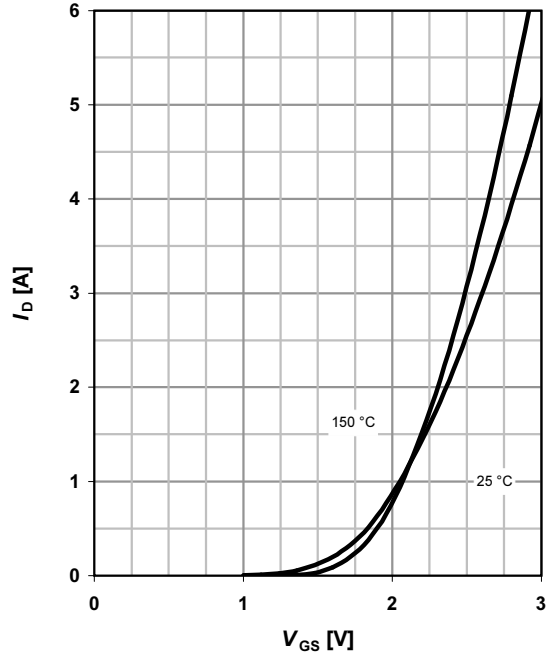
parameter: T_j



14 Typ. transfer characteristics (N)

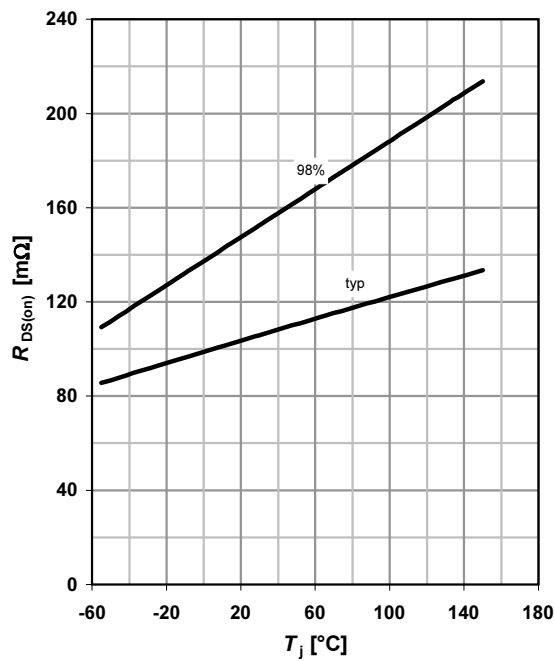
$$I_D = f(V_{GS}); |V_{DS}| > 2 |I_D| R_{DS(on)max}$$

parameter: T_j



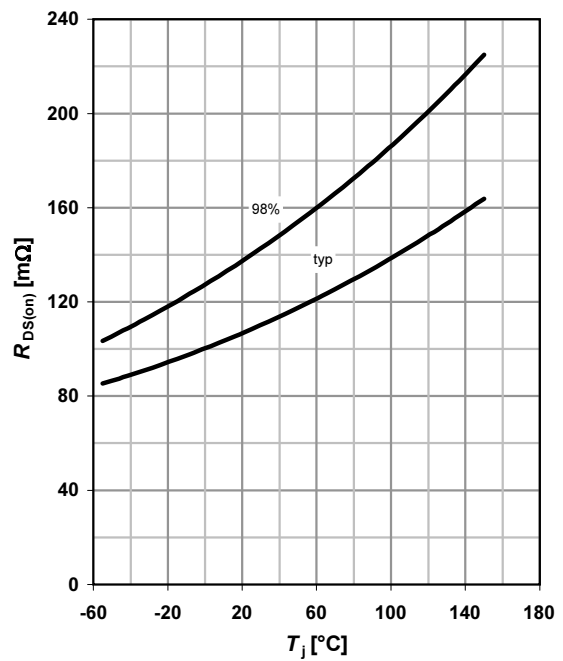
15 Drain-source on-state resistance (P)

$$R_{DS(on)} = f(T_j); I_D = -1.5 \text{ A}; V_{GS} = -4.5 \text{ V}$$



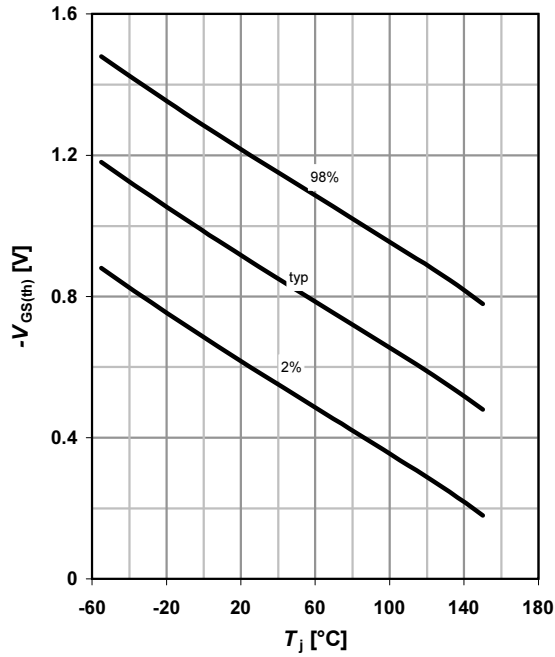
16 Drain-source on-state resistance (N)

$$R_{DS(on)} = f(T_j); I_D = 1.5 \text{ A}; V_{GS} = 4.5 \text{ V}$$



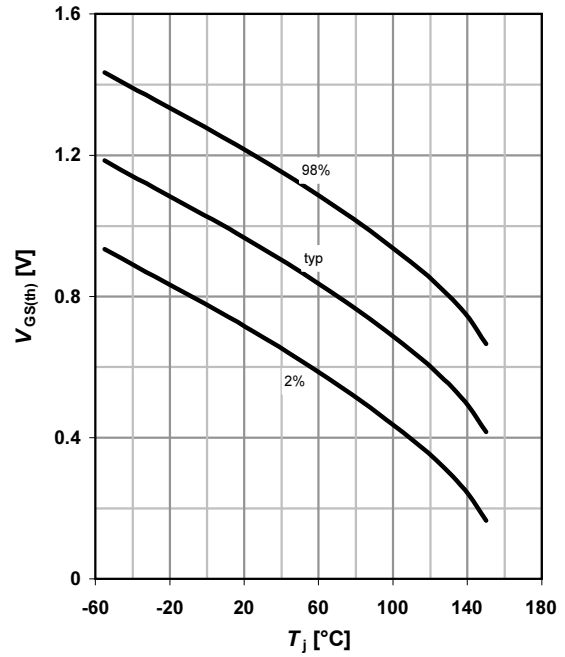
17 Typ. gate threshold voltage (P)

$V_{GS(th)}=f(T_j); V_{GS}=V_{DS}; I_D=-11 \mu A$



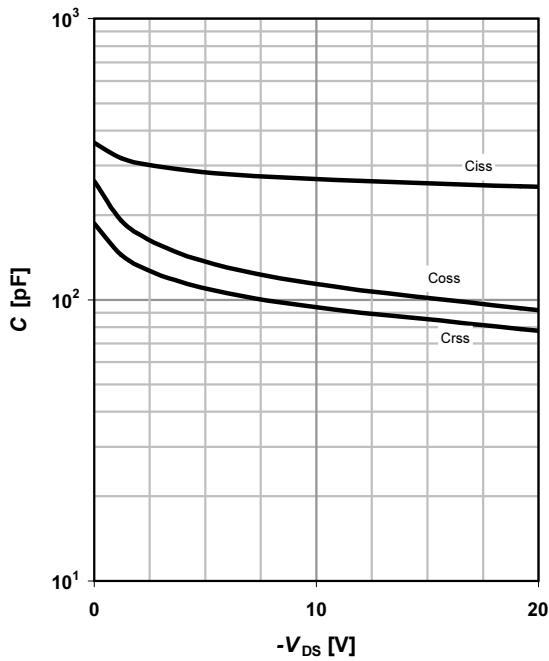
18 Typ. gate threshold voltage (N)

$V_{GS(th)}=f(T_j); V_{GS}=V_{DS}; I_D=3.7 \mu A$



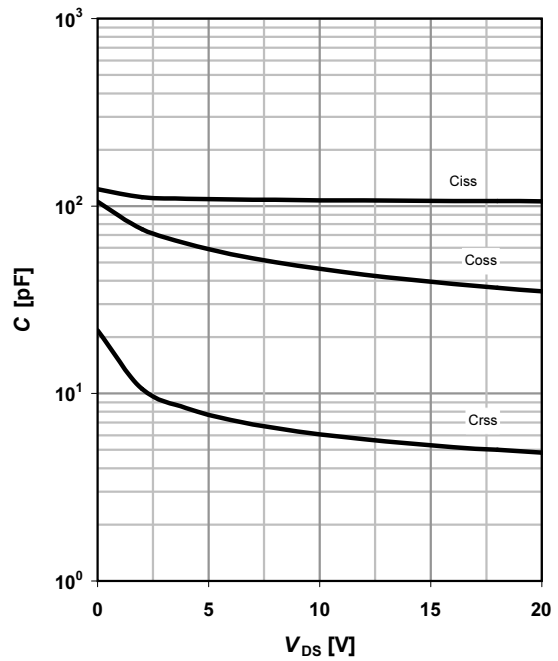
19 Typ. capacitances (P)

$C=f(V_{DS}); V_{GS}=0 V; f=1 MHz$



20 Typ. capacitances (N)

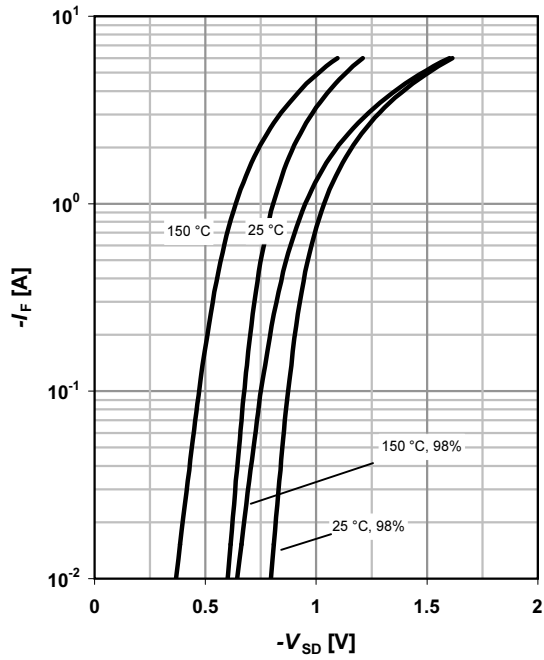
$C=f(V_{DS}); V_{GS}=0 V; f=1 MHz$



21 Forward characteristics of reverse diode (P)

$I_F=f(V_{SD})$

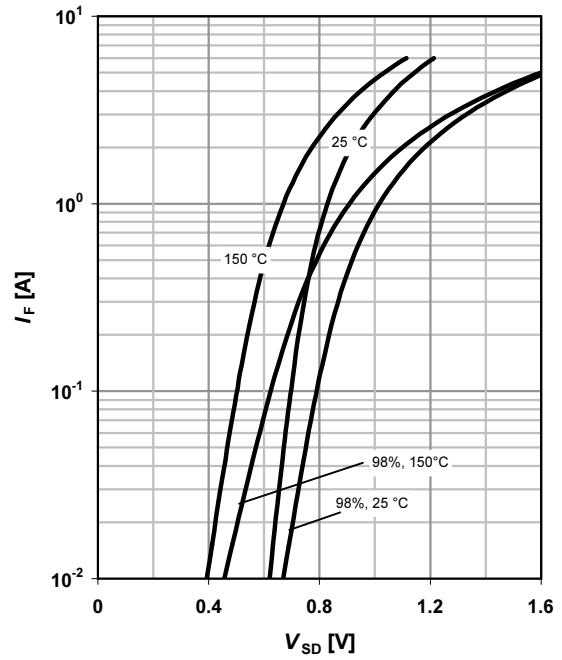
parameter: T_j



22 Forward characteristics of reverse diode (N)

$I_F=f(V_{SD})$

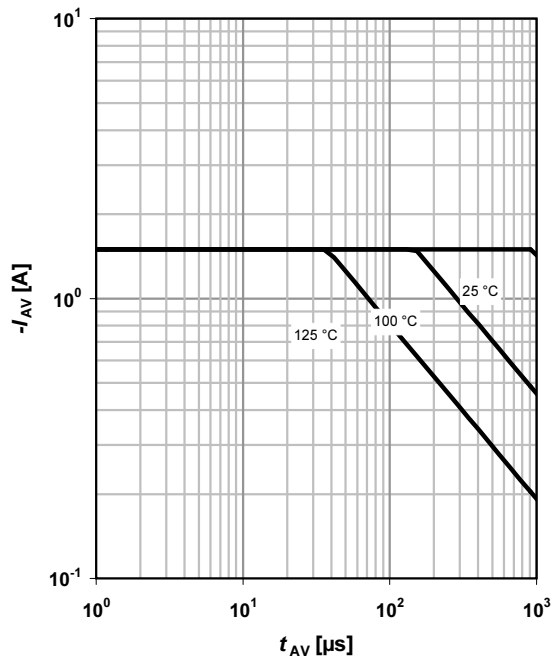
parameter: T_j



23 Avalanche characteristics (P)

$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$

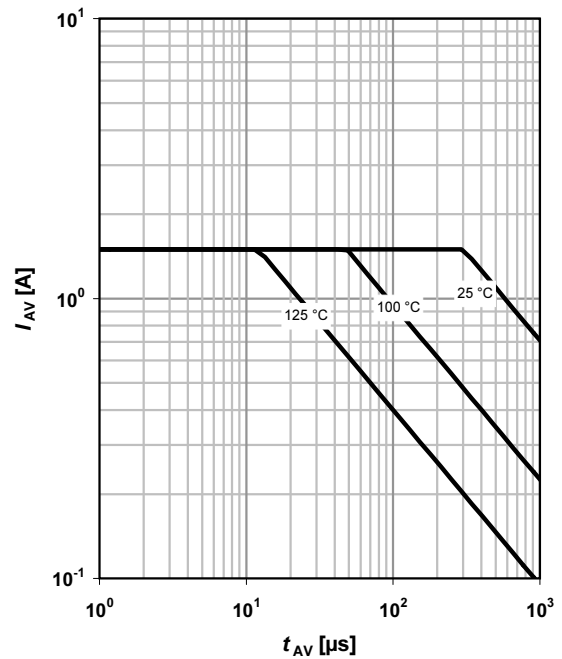
parameter: $T_{j(start)}$



24 Avalanche characteristics (N)

$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$

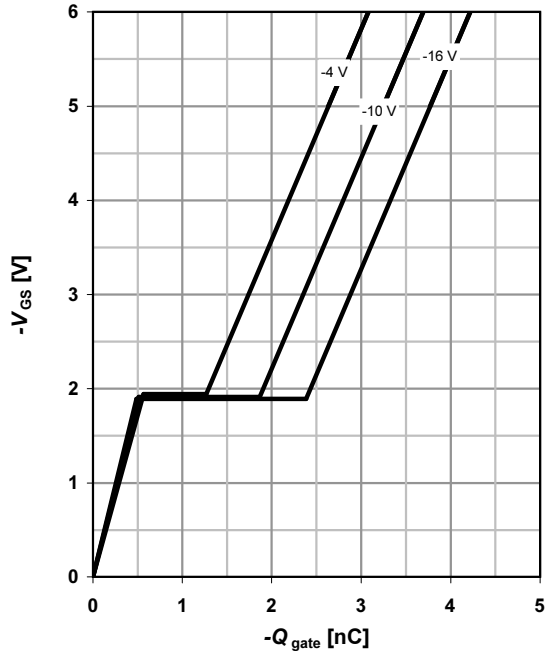
parameter: $T_{j(start)}$



25 Typ. gate charge (P)

$V_{GS}=f(Q_{gate}); I_D=-1.5\text{ A pulsed}$

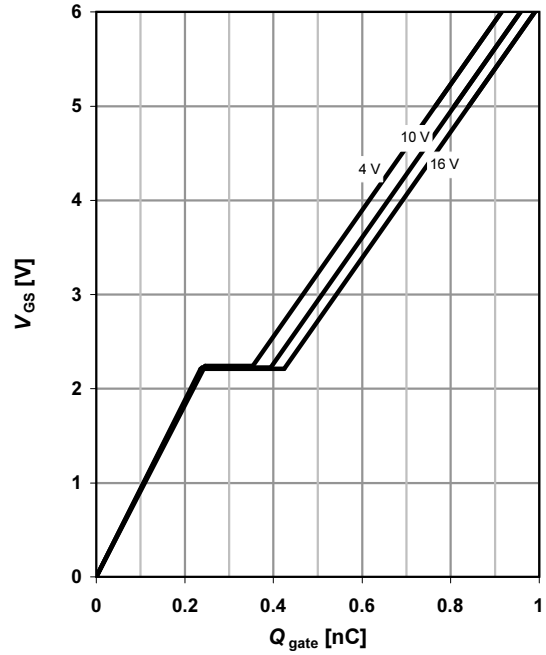
parameter: V_{DD}



26 Typ. gate charge (N)

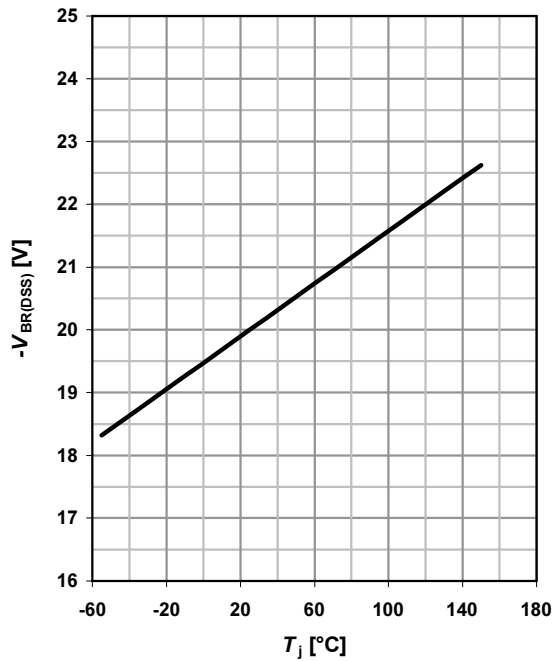
$V_{GS}=f(Q_{gate}); I_D=1.5\text{ A pulsed}$

parameter: V_{DD}



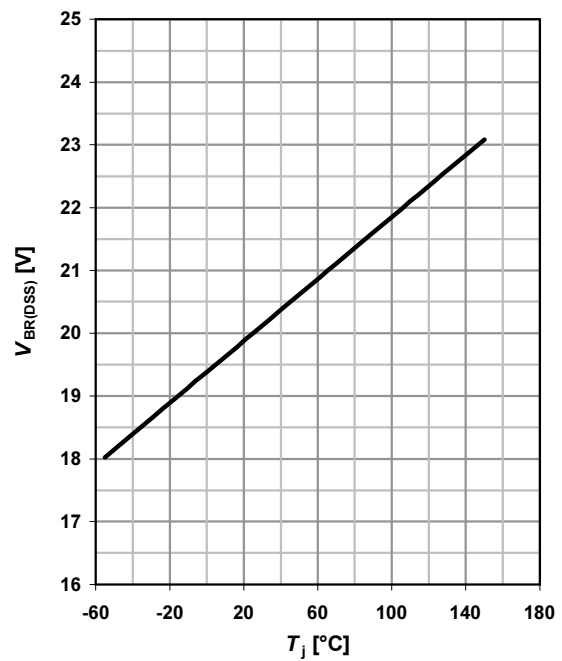
27 Drain-source breakdown voltage (P)

$V_{BR(DSS)}=f(T_j); I_D=-250\ \mu\text{A}$



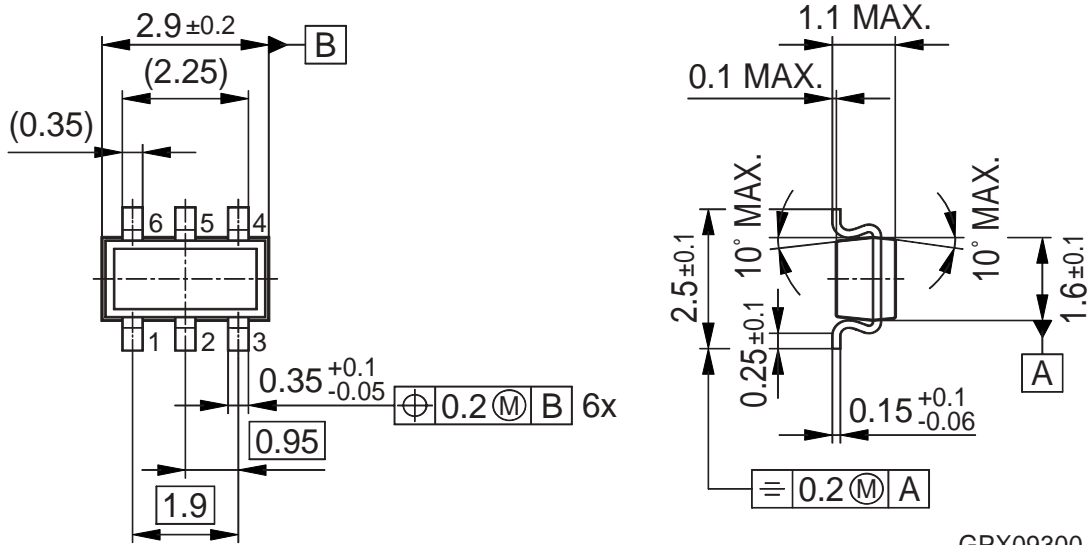
28 Drain-source breakdown voltage (N)

$V_{BR(DSS)}=f(T_j); I_D=250\ \mu\text{A}$

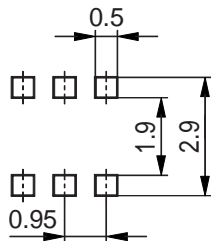


TSOP6

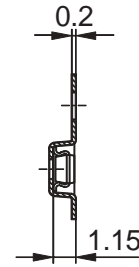
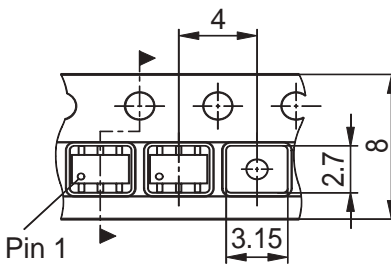
Package Outline:



Footprint:



Packaging:



Remark: Wave soldering possible dep. on customers process conditions

HLG09283

CPWG5899

Dimensions in mm

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